Interface Electronics

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Outline



Update to backplane

Signal transfer ASIC to analogue chain

- Simulations
- Impacts to circuit diagram
- Drawbacks

Personal view



Update to backplane





Not available would need a more complex design inside the vacuum.

A ring more for the HV: while defining the footprint. Close to MIL-norm

As consequence a bit of resorting at the left end





> Open issue: - Kind of signal source (ASIC) : I, U, Z

- Kind of termination at interface electronics

Distance between ASIC and Receiver:

Open issue, but 10cm wide module Voltage-reg. in the vacuum (10cm) three connectors (7 cm) trace in Interface electronics 2cm trace on HDI

30 cm might be a bit too pessimistic but not too far from reality

= 2ns per signal pass





Signal transfer: Assembly blocks







Signal transfer: Transfer line model





18 elements for 2ns: $L^*C = 2ns/18$ $Z^2 = (100\Omega)^2 = L/C$



Signal transfer: U_source, U_receiver





Signal transfer: Z_source, U_receiver







Signal transfer: I_source, I_receiver







Signal transfer: Z_source, I_receiver







Signal transfer: Sampling rate reduction





Signal transfer: Sampling rate reduction



Drawback or best compromise?

- Good storage behaviour:
 - Can it be used to increase the number of storage cells?

400 Cells @ 50MS/s needs 16.4ms for digitizing. 10MS/s possible

But: Giving "just" up the option for 30Hz train rate.

Giving up 512 Cells @ 10Hz train rate, just not possible.

Would smaller storage cell needs less storage time?

To stay with 50MS/s the interface might need a design like: Transferring a start address and doing than ASIC-internal increments for 16 (32) pulses while digitizing.

Digital part of interface would get a little bit easier, for lower sampling rate.



Signal transfer: Frequency domain, Voltage



Resonances increases sensitivity to pickup noise

on the full system level



Signal transfer: Frequency domain, Current



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Signal transfer: Impact to analogue part: Basic circuit (terminated U-type)



Power consumption requires ONE amplifier solution

Filtering : e.g. Noise picked up between ASIC and Interface electronics:

- Before amplifier
- In feedback
- Between Amplifier and ADC

Need DC-coupling: During long digitizing sequence for a train Best with pedestal samples delivered from ASIC.

Baseline from ASIC as pull to one side: -0.9V or just above -1.0V

ASIC handles, that the feedback delivers common mode: 0.9V, 470Ω Peter Göttlicher | Interface electronics | March 8th 2011 | Page 1



Signal transfer: Impact to analogue part: U – Receiver: not terminated





Remaining impedance keeping the rest like it is: around $1k\Omega$



Signal transfer: Impact to analogue part: I – Receiver: not terminated





Whole part of the input filter disappears

Two small resistors to the input pins to limit long antennas on the input pins.

- But all the reflection problem.
- Trans-impedance: $1k\Omega$ is possible.



Signal transfer: Impact to analogue part: Basic circuit (terminated U-type)



What about doing the termination, but

reducing the dynamics of the ASIC 50MHz: Noise: 0.35mV

- 100MHz: Noise 0.53mV
- 400mV needed to keep 9-10bit instead of the 2V foreseen.

>-200mV for baseline <+200mV for full scale

More noise pickup between ASIC and receiver.



Table 11. Recommended Resistor Values and Nois	se
Performance for Specific Gains	

	Gain	R _G (Ω)	R _F (Ω)	Bandwidth –3 dB (MHz)	Output Noise AD8132 Only (nV/√Hz)	Output Noise AD8132 + R _G , R _F (nV/√Hz)
	1	499	499	360	16	17
	2	499	1.0 k	160	24.1	26.1
<	5	499	2.49 k	65	48.4	53.3
	10	499	4.99 k	20	88.9	98.6

Signal transfer: Other input chip - same function, keeping single chip/channel

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ADA4938-1/ADA4938-2

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More noise pickup between ASIC and receiver.

Lower Noise would be available:

Table 10 and Table 11 list several common gain settings, associated resistor values, input impedances, and output noise densities for both balanced and unbalanced input configurations. Also shown

s, and output noise densities for Cost: Higher power -

Nominal Gain (V/V)	R⊧(Ω)	R ₆ (Ω)	RiN, dm (Ω)	Output Noise Density (nV/√Hz)
1	200	200	400	6.5
2	402	200	400	10.4
3.16	402	127	254	13.4
5	402	80.6	161	(18.2

Table 10. Differential Ground-Referenced Input, DC-Coupled; See

Cost: Higher power ~300-500W for 1Mpixel

No similar for same footprint

Different project searches ended up with same chip: Alternative in concept?

Higher bandwidth: (?) more sensitive to couple input lines with low impedance:(?) No ideal I-receiver



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Signal transfer: Addional input chip Very low receiver-Noise or just a factor 2

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Lower Noise would be available:

Cost: Higher power 100A: ~500W-700W for 1Mpixel

+ Few centimeters.

Input impedance is external resistor

Internal virtual "infinity" to "200 Ω "

ONLY chip noise: not power or pickup

LT6411 would offer an option for gain 3 gain (only input 8nV/sqrt(Hz), gain 2) 60W/1Mega-Pixel + few cm's





DES



- I would not go the way of reflections and the according oscillations
- "Huge"power will change the mechnaical concept: Add as in first option: Water-cooling onto the module and not only onto the frame.
- What are the drawbacks of an impedance controlled driver? what about a limited amplitude?
- I would like to keep the option of maximized the frame rate That is not a statement, that somebody is not fighting for it. Does it need short storage times?

